

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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Title of Invention

PARTIAL WAFER BONDING AND DICING

Application Number :

Confirmation Number:

First Named Applicant: Louis Hsu

Attorney Docket Number: FIS920040114US1

Art Unit:

Examiner:

Search string: (4962879 or 6004866 or 6010591 or 6013534 or 6538330 or 6616854).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	4962879	1990-10-16	Goesele et al			
	2	6004866	1999-12-21	Nakano et al			
	3	6010591	2000-01-04	Gosele			
	4	6013534	2000-01-11	Mountain			
	5	6538330	2003-03-25	Forbes			
	6	6616854	2003-09-09	Jones et al			

Signature

Examiner Name	Date